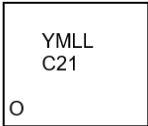
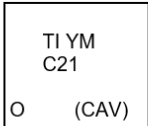


<b>PCN Number:</b>	20240202002.1		<b>PCN Date:</b>	February 02, 2024	
<b>Title:</b>	Qualification of RFAB using qualified Process Technology, Die Revision and additional Assembly Site for select devices				
<b>Customer Contact:</b>	Change Management team		<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 2, 2024	<b>Estimated Sample Availability:</b>	Mar 2, 2024*		
<b>*Sample requests received after March 2, 2024 will not be supported.</b>					
<b>Change Type:</b>					
<input checked="" type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material	
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process	
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process	
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology in addition to an Assembly site option for the devices listed below.					
<b>Current Fab Site</b>			<b>Additional Fab Site</b>		
<b>Current Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>	<b>Additional Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>
GFAB6/8	P2CMOS	150/200 mm	RFAB	LBC9	300 mm
DFAB		200 mm			
The die was also changed as a result of the process change.					
Additionally, there will be Assembly site & BOM options introduced for these devices as follows:					
	<b>TIEM</b>	<b>MLA</b>			
Wire diam/type	0.96mil Cu	0.80 mil Cu			
Mount compound	8075531	4147858			
Mold Compound	8096859	4211880			
Lead finish	Matte Sn	NiPdAu			
ECAT	G3	G4			
Package marking change:					
	<b>Current</b>	<b>Proposed</b>			
<b>Package Marking (Sample)</b>					
	YM = YEAR MONTH DATE CODE LL = ASSEMBLY LOT CODE O = PIN 1 INDICATOR	TI = TI LETTERS YM = YEAR MONTH DATE CODE O = PIN 1 INDICATOR CAV = CAVITY NUMBER			
Qual details are provided in the Qual Data Section.					
<b>Reason for Change:</b>					
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive /</b>					

<b>negative):</b>
None

Impact on Environmental Ratings:			
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			
<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change
Changes to product identification resulting from this PCN:			
<b>Fab Site Information:</b>			
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock
GFAB8	GF8	GBR	Greenock
DFAB	DLN	USA	Dallas
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>
<b>Die Rev:</b>			
<b>Current</b>		<b>New</b>	
Die Rev [2P]	Die Rev [2P]		
C	C		
<b>Assembly Site Information:</b>			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TIEMA	CU6	MYS	Melaka
<b>MLA</b>	<b>MLA</b>	<b>MYS</b>	<b>Kuala Lumpur</b>
Sample product shipping label (not actual product label)			
Product Affected:			
LMC6772AIMM/NOPB	LMC6772AIMMX/NOPB		

For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LMC6772AIMMX/NOPB	QBS Reference: OPA2205ADGKR	QBS Reference: OPA2206ADGKR	QBS Reference: BQ79616PAPRQ1	QBS Reference: TLV1812QDGKRQ1	QBS Reference: TLV1822QDGKRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	2/154/0	-	1/77/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	1/77/0	2/154/0	-	1/77/0	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	1/77/0	2/154/0	-	1/77/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	1/77/0	2/154/0	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	1/77/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	1/77/0	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/6/0	1/6/0
FTY	E6	Final Test Yield	-	-	Pass	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device LMC6772AIMMX/NOPB is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2312-001

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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